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SEMICONDUCTOR



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PLED

Product data sheet

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SMA

FEATURES

- * Ideal for surface mount applications
- * Easy pick and place
- * Built-in strain relief
- * Low forward voltage drop

MECHANICAL DATA

- * Case: Molded plastic
- * Epoxy: UL 94V-0 rate flame retardant
- * Metallurgically bonded construction
- * Polarity: Color band denotes cathode end
- * Mounting position: Any
- * Weight: 0.063 grams

MAXIMUM RATINGS AND ELECTRICAL CHARACTERISTICS

Rating 25°C ambient temperature unless otherwise specified.
 Single phase half wave, 60Hz, resistive or inductive load.
 For capacitive load, derate current by 20%.

TYPE NUMBER	SS215	SS220	UNITS
Maximum Recurrent Peak Reverse Voltage	150	200	V
Maximum RMS Voltage	105	140	V
Maximum DC Blocking Voltage	150	200	V
Maximum Average Forward Rectified Current at $T_L=100^\circ\text{C}$	2.0		A
Peak Forward Surge Current, 8.3 ms single half sine-wave superimposed on rated load (JEDEC method)	50		A
Maximum Instantaneous Forward Voltage at 2.0A	0.92		V
Maximum DC Reverse Current $T_a=25^\circ\text{C}$	0.02		mA
at Rated DC Blocking Voltage $T_a=100^\circ\text{C}$	2		mA
Typical Junction Capacitance (Note 1)	170		PF
Typical Thermal Resistance $R_{\theta JL}$ (Note 2)	12		$^\circ\text{C}/\text{W}$
Operating Temperature Range T_j	-65 — +150		$^\circ\text{C}$
Storage Temperature Range T_{STG}	-65 — +150		$^\circ\text{C}$

NOTES:

1. Measured at 1MHz and applied reverse voltage of 4.0V D.C.
2. Thermal Resistance Junction to Lead Vertical PC Board Mounting 0.375"(9.5mm) Lead Length.

RATING AND CHARACTERISTIC CURVES (SS215 THRU SS220)

FIG.1-TYPICAL FORWARD CURRENT DERATING CURVE

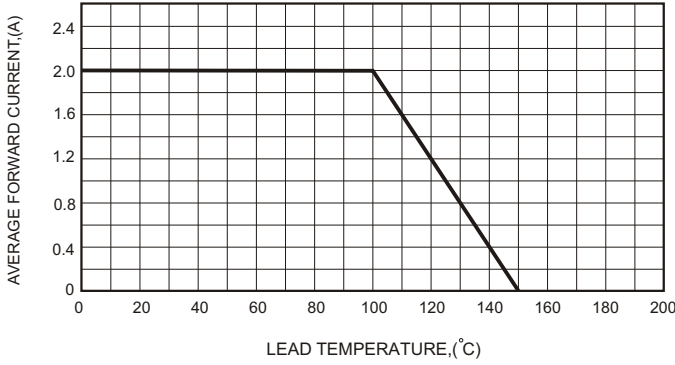


FIG.2-TYPICAL FORWARD CHARACTERISTICS

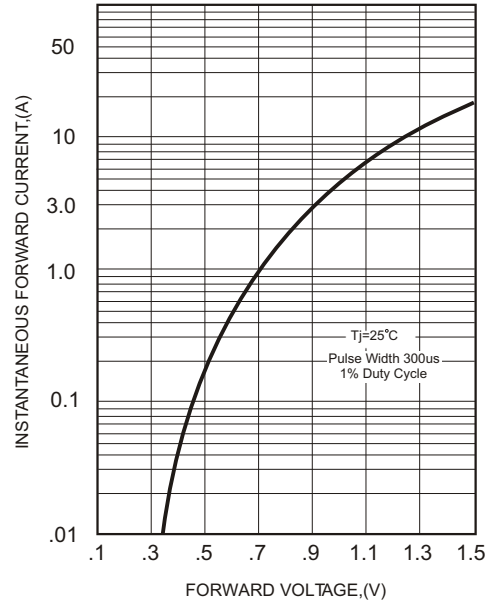


FIG.3-MAXIMUM NON-REPETITIVE FORWARD SURGE CURRENT

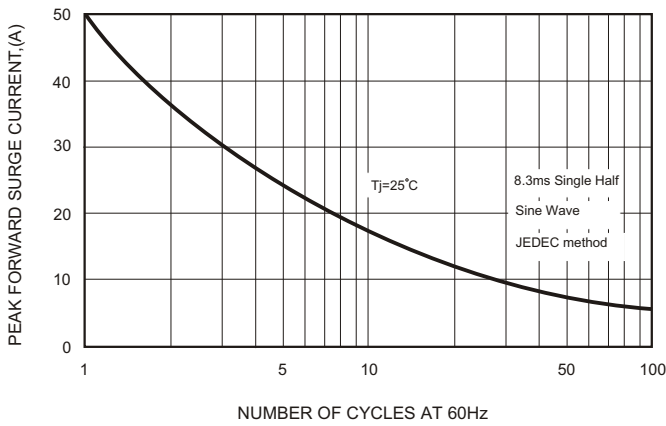


FIG.4-TYPICAL JUNCTION CAPACITANCE

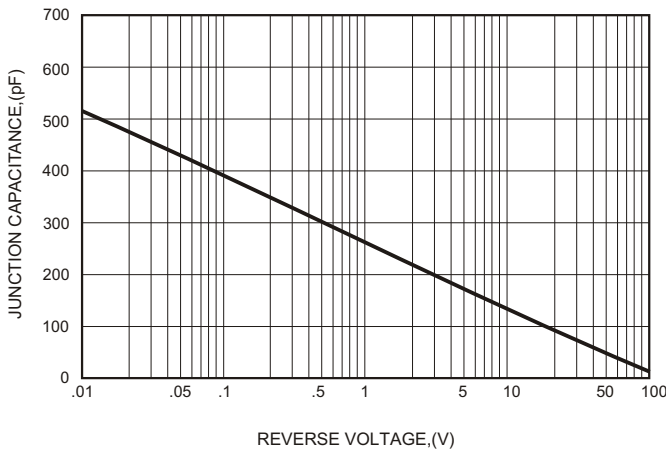
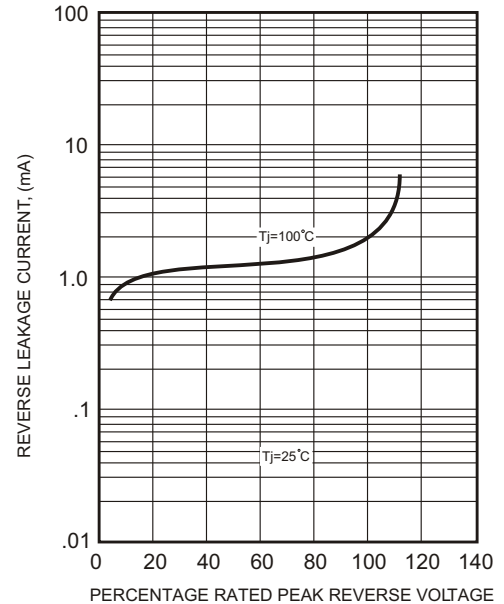
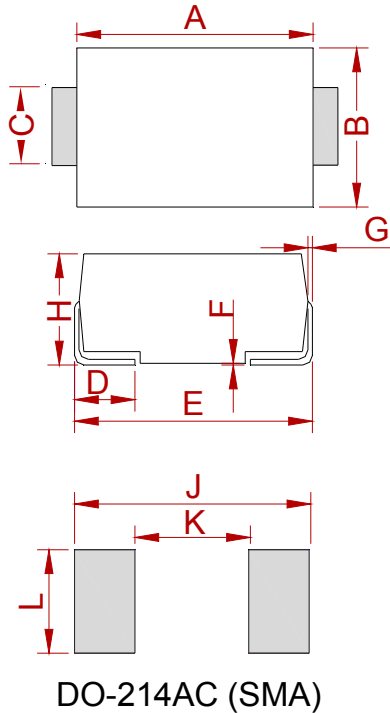


FIG.5 - TYPICAL REVERSE CHARACTERISTICS



PACKAGE MECHANICAL DATA



Ref.	Dimensions			
	Millimeters		Inches	
	Min.	Max.	Min.	Max.
A	4.25	4.65	0.167	0.183
B	2.50	2.90	0.098	0.114
C	1.35	1.65	0.053	0.065
D	0.76	1.52	0.030	0.060
E	4.93	5.28	0.194	0.208
F	0.051	0.203	0.002	0.008
G	0.15	0.31	0.006	0.012
H	1.98	2.41	0.078	0.095
J	6.50		0.256	
K		2.30		0.090
L	1.70		0.067	

REEL SPECIFICATION

P/N	PKG	QTY
SS215 THRU SS220	SMA	2000

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